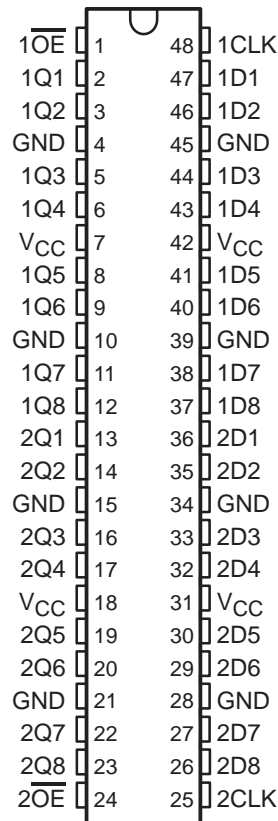


SN54AHC16374, SN74AHC16374 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCLS330G – MARCH 1996 – REVISED JANUARY 2000

- **Members of the Texas Instruments Widebus™ Family**
- **EPIC™ (Enhanced-Performance Implanted CMOS) Process**
- **Operating Range 2-V to 5.5-V V_{CC}**
- **3-State Outputs Drive Bus Lines Directly**
- **Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54AHC16374 . . . WD PACKAGE
SN74AHC16374 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The 'AHC16374 devices are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

\overline{OE} does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN54AHC16374 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AHC16374 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC and Widebus are trademarks of Texas Instruments Incorporated.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2000, Texas Instruments Incorporated

SN54AHC16374, SN74AHC16374

16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOPS

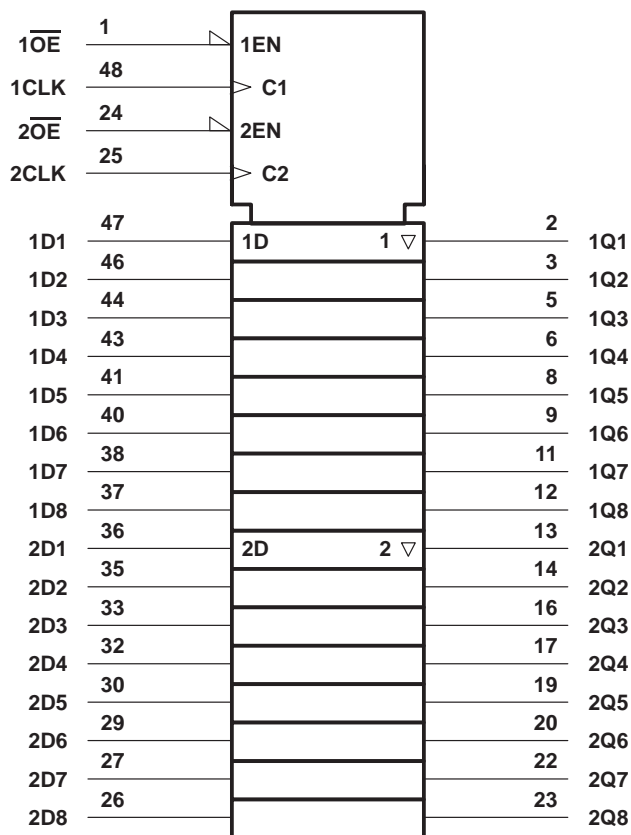
WITH 3-STATE OUTPUTS

SCLS330G – MARCH 1996 – REVISED JANUARY 2000

FUNCTION TABLE
(each 8-bit flip-flop)

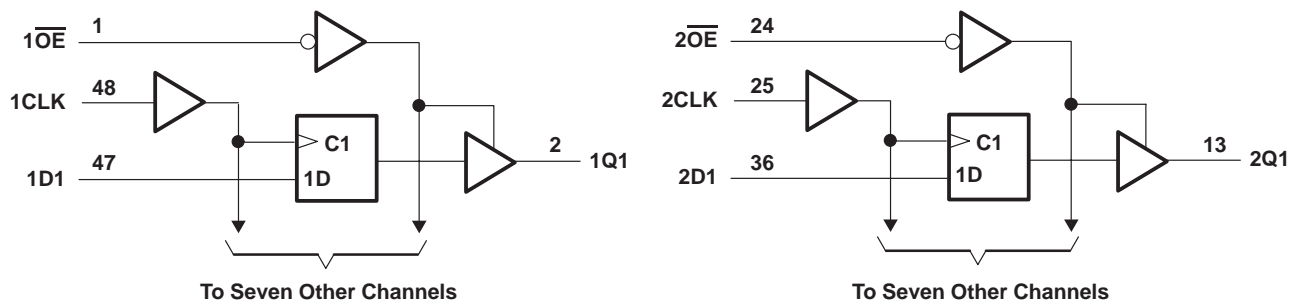
INPUTS			OUTPUT
\overline{OE}	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



SN54AHC16374, SN74AHC16374 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCLS330G – MARCH 1996 – REVISED JANUARY 2000

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through each V_{CC} or GND	±75 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	70°C/W
DGV package	58°C/W
DL package	63°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		SN54AHC16374		SN74AHC16374		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2	5.5	2	5.5	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V		1.5		V
		$V_{CC} = 3$ V		2.1		
		$V_{CC} = 5.5$ V		3.85		
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V		0.5		V
		$V_{CC} = 3$ V		0.9		
		$V_{CC} = 5.5$ V		1.65		
V_I	Input voltage	0	5.5	0	5.5	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2$ V		–50		μ A
		$V_{CC} = 3.3$ V ± 0.3 V		–4		mA
		$V_{CC} = 5$ V ± 0.5 V		–8		
I_{OL}	Low-level output current	$V_{CC} = 2$ V		50		μ A
		$V_{CC} = 3.3$ V ± 0.3 V		4		mA
		$V_{CC} = 5$ V ± 0.5 V		8		
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3.3$ V ± 0.3 V		100		ns/V
		$V_{CC} = 5$ V ± 0.5 V		20		
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54AHC16374, SN74AHC16374

16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOPS

WITH 3-STATE OUTPUTS

SCLS330G – MARCH 1996 – REVISED JANUARY 2000

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHC16374		SN74AHC16374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	2 V	1.9	2		1.9		1.9	V	
		3 V	2.9	3		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		
	I _{OH} = -4 mA	3 V	2.58			2.48		2.48		
	I _{OH} = -8 mA	4.5 V	3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 μA	2 V			0.1		0.1		V	
		3 V			0.1		0.1			
		4.5 V			0.1		0.1			
	I _{OL} = 4 mA	3 V			0.36		0.5	0.44		
	I _{OL} = 8 mA	4.5 V			0.36		0.5	0.44		
I _I	V _I = V _{CC} or GND	0 V to 5.5 V			±0.1		±1*		μA	
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.25		±2.5		μA	
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		40		μA	
C _i	V _I = V _{CC} or GND	5 V		2.5	10			10	pF	
C _o	V _O = V _{CC} or GND	5 V		3.5					pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		SN54AHC16374		SN74AHC16374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, CLK high or low	5		5.5		5.5		ns
t _{su}	Setup time, data before CLK↑	4.5		4		4		ns
t _h	Hold time, data after CLK↑	2		2		2		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		SN54AHC16374		SN74AHC16374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, CLK high or low	5		5		5		ns
t _{su}	Setup time, data before CLK↑	3		3		3		ns
t _h	Hold time, data after CLK↑	2		2		2		ns

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN54AHC16374, SN74AHC16374
16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOPS
WITH 3-STATE OUTPUTS

SCLS330G – MARCH 1996 – REVISED JANUARY 2000

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3 V \pm 0.3 V$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHC16374		SN74AHC16374		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{\max}			$C_L = 15 \text{ pF}$	80*	130*		70*		70		MHz
			$C_L = 50 \text{ pF}$	55	85		50		50		
t_{PLH}	CLK	Q	$C_L = 15 \text{ pF}$		9*	15*	1*	17*	1	17	ns
t_{PHL}					9*	15*	1*	17*	1	17	
t_{PZH}	$\overline{\text{OE}}$	Q	$C_L = 15 \text{ pF}$		8*	13*	1*	15*	1	15	ns
t_{PZL}					8*	13*	1*	15*	1	15	
t_{PHZ}	$\overline{\text{OE}}$	Q	$C_L = 15 \text{ pF}$		9*	14*	1*	16*	1	16	ns
t_{PLZ}					10*	14*	1*	16*	1	16	
t_{PLH}	CLK	Q	$C_L = 50 \text{ pF}$		10.6	16.2	1	18.5	1	18.5	ns
t_{PHL}					10.6	16.2	1	18.5	1	18.5	
t_{PZH}	$\overline{\text{OE}}$	Q	$C_L = 50 \text{ pF}$		9.6	14.9	1	16	1	16	ns
t_{PZL}					9.6	14.9	1	16	1	16	
t_{PHZ}	$\overline{\text{OE}}$	Q	$C_L = 50 \text{ pF}$		10.2	15.5	1	17	1	17	ns
t_{PLZ}					11.8	15.5	1	17	1	17	
$t_{\text{sk(o)}}$			$C_L = 50 \text{ pF}$			1.5**				1.5	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5 V \pm 0.5 V$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHC16374		SN74AHC16374		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{\max}			$C_L = 15 \text{ pF}$	130*	185*		110*		110		MHz
			$C_L = 50 \text{ pF}$	85	120		75		75		
t_{PLH}	CLK	Q	$C_L = 15 \text{ pF}$		5.4*	9.1*	1*	10.1*	1	10.1	ns
t_{PHL}					5.4*	9.1*	1*	10.1*	1	10.1	
t_{PZH}	$\overline{\text{OE}}$	Q	$C_L = 15 \text{ pF}$		5.1*	9.1*	1*	10.1*	1	10.1	ns
t_{PZL}					5.1*	9.1*	1*	10.1*	1	10.1	
t_{PHZ}	$\overline{\text{OE}}$	Q	$C_L = 15 \text{ pF}$		5*	9.5*	1*	10.5*	1	10.5	ns
t_{PLZ}					5*	9.5*	1*	10.5*	1	10.5	
t_{PLH}	CLK	Q	$C_L = 50 \text{ pF}$		6.9	10.1	1	11.5	1	11.5	ns
t_{PHL}					6.9	10.1	1	11.5	1	11.5	
t_{PZH}	$\overline{\text{OE}}$	Q	$C_L = 50 \text{ pF}$		6.6	10.1	1	11.5	1	11.5	ns
t_{PZL}					6.6	10.1	1	11.5	1	11.5	
t_{PHZ}	$\overline{\text{OE}}$	Q	$C_L = 50 \text{ pF}$		6.1	10.5	1	11.5	1	11.5	ns
t_{PLZ}					6.1	10.5	1	11.5	1	11.5	
$t_{\text{sk(o)}}$			$C_L = 50 \text{ pF}$			1**				1	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN54AHC16374, SN74AHC16374
16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOPS
WITH 3-STATE OUTPUTS

SCLS330G – MARCH 1996 – REVISED JANUARY 2000

noise characteristics, $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 4)

PARAMETER	SN74AHC16374			UNIT
	MIN	TYP	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic V_{OL}		0.36	0.8	V
$V_{OL(V)}$ Quiet output, minimum dynamic V_{OL}		-0.16	-0.8	V
$V_{OH(V)}$ Quiet output, minimum dynamic V_{OH}		4.6		V
$V_{IH(D)}$ High-level dynamic input voltage	3.5			V
$V_{IL(D)}$ Low-level dynamic input voltage			1.5	V

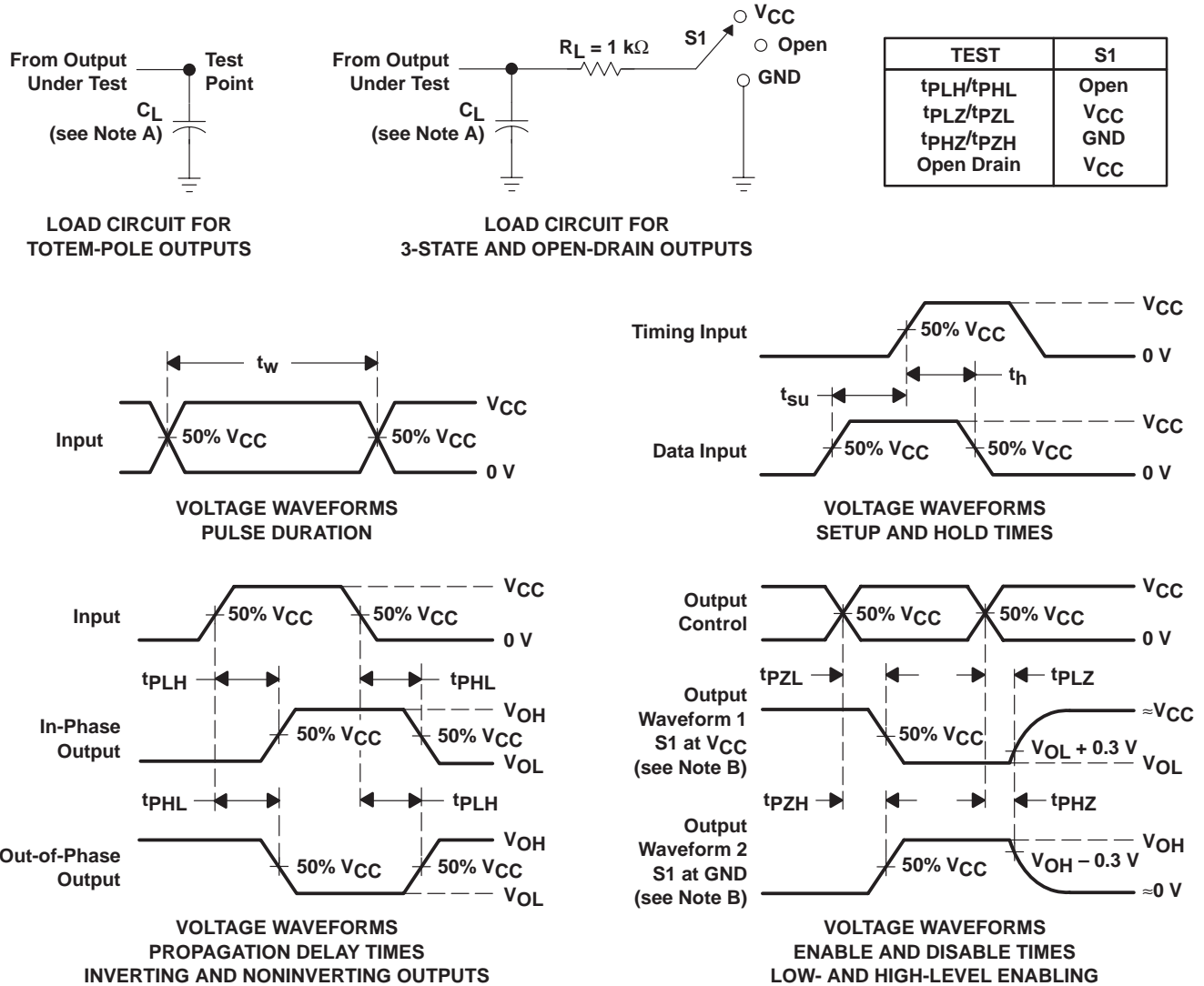
NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	32	pF



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is high except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is low except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AHC16374DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHC16374DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHC16374DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHC16374DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16374DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16374DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16374DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16374DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16374DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16374DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL BOX INFORMATION



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC16374DGGR	DGG	48	SITE 41	330	24	8.6	15.8	1.8	12	24	Q1
SN74AHC16374DGVR	DGV	48	SITE 41	330	24	6.8	10.1	1.6	12	24	Q1
SN74AHC16374DLR	DL	48	SITE 41	330	32	11.35	16.2	3.1	16	32	Q1

TAPE AND REEL BOX DIMENSIONS



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74AHC16374DGGR	DGG	48	SITE 41	346.0	346.0	41.0
SN74AHC16374DGVR	DGV	48	SITE 41	346.0	346.0	41.0
SN74AHC16374DLR	DL	48	SITE 41	346.0	346.0	49.0

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
Low Power Wireless	www.ti.com/lpw	Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2007, Texas Instruments Incorporated